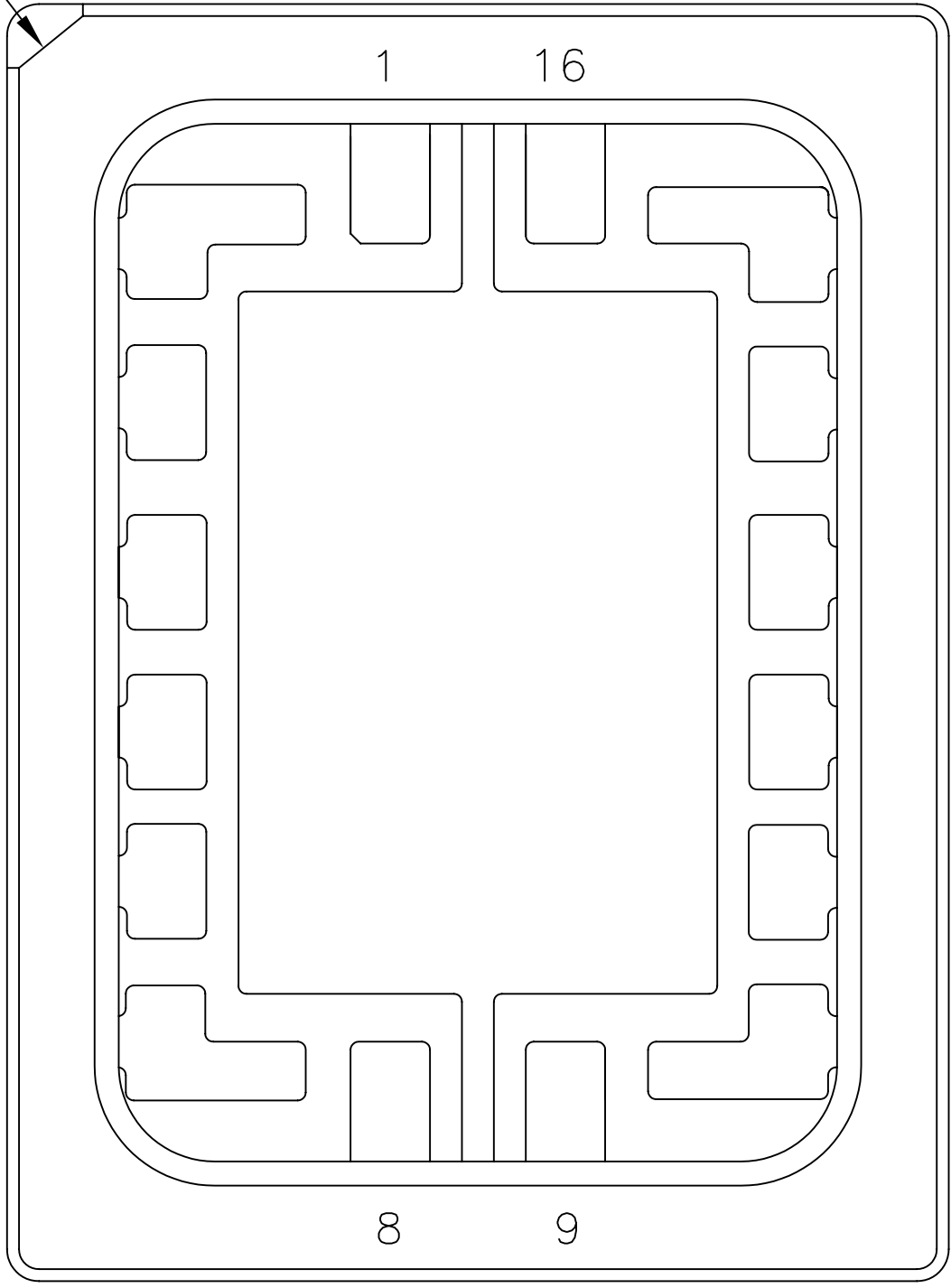


PIN #1 IDENTIFIER



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006						
CUSTOMER:			DIE SIZE:					16 Lead 300 mils SOIC Open-Pak Bonding Diagram		
WIRE TYPE/ SIZE:			NO. OF WIRES:							
THIRD ANGLE PROJECTION		REVISIONS				SIZE A PART NO. SOIC300-16-OP-01 REV 2				
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. DO NOT SCALE DRAWING		ECN NO.	DATE	DESCRIPTION	APPROVED	SCALE 30X CAD FILE SOIC300-16-OP-01-B-R2.DWG SHEET 1 OF 1				
		10512	11/2/05	PRODUCTION RELEASE	D.BENANDO					
DRAWN BY	W. GRIFFITTS	DATE	11/1/05	PACKAGE SIZE:	0.100" x 0.295"					
APP BY	P. FLASKERUD	DATE	11/1/05	DIE PAD SIZE:	0.150" x 0.220"					